



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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A

B

C

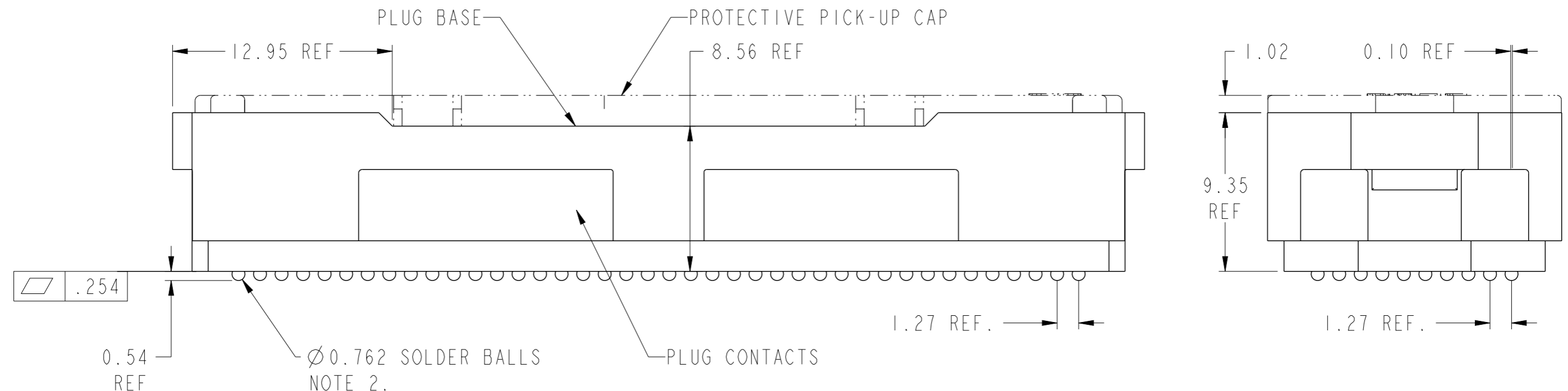
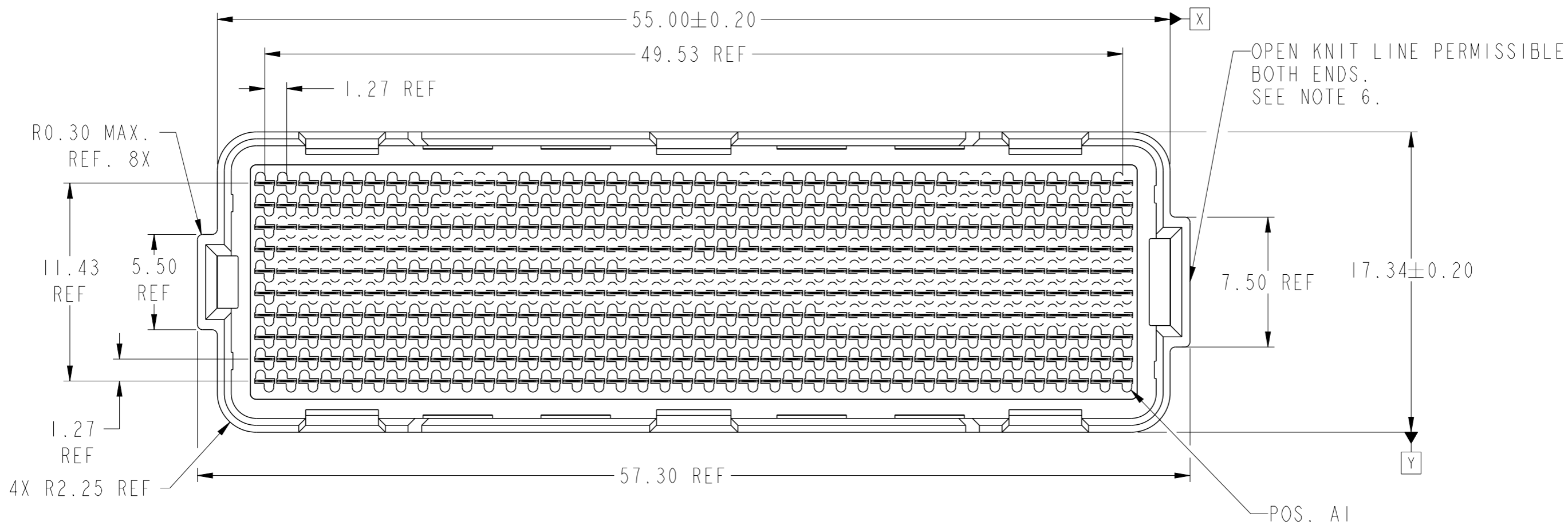
D

A

B

C

D



⊕ ⊘ .30 X Y

spec ref	-	dr	wcadmin	1999/08/19	projection	mm	size	A3	scale	4:1	
tolerance std	ASME Y14.5	eng	Dave Horchler	2012/11/21			ecn no	ELX-V-13515-1			
	TOLERANCES UNLESS OTHERWISE SPECIFIED	chr	-	product family				MEG-ARRAY	rel level	Released	
surface	✓	appr	R Marshall	2012/11/27			dwg no	84520		rev	H
ASME Y14.5	linear	www.fci.com		cat. no.	6.0mm PLUG ASSEMBLY		Product - Customer Drw		sheet 1 of 5		
	angular				10 X 40 = 400 POSITIONS		STATUS: Released		Printed: Nov 28, 2012		



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A

B

C

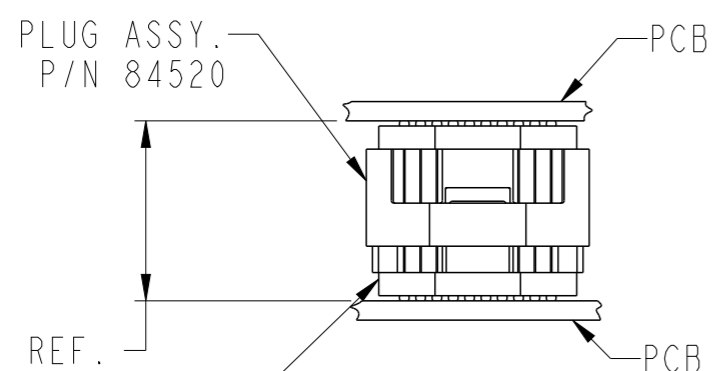
D

A

B

C

D

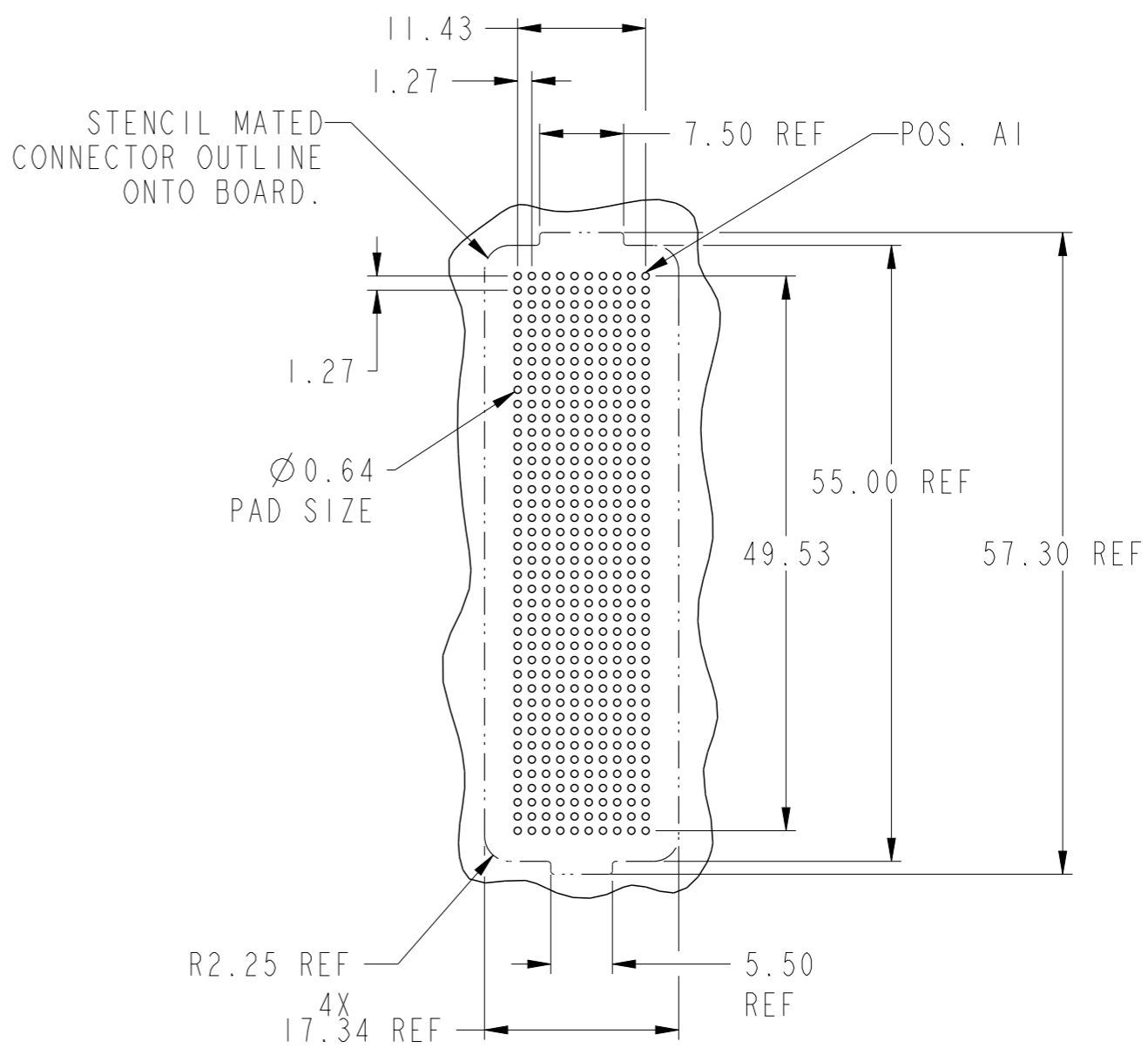


DIM "A" REF.
MATED HEIGHT
AFTER REFLOW
SEE NOTE 3.

END VIEW - MATED CONNECTORS

MATED HEIGHT AFTER REFLOW IS BASED ON Ø0.64mm PAD (METAL DEFINED) AND 0.13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

RECPT. ASSY.
(SEE TABLE BELOW)



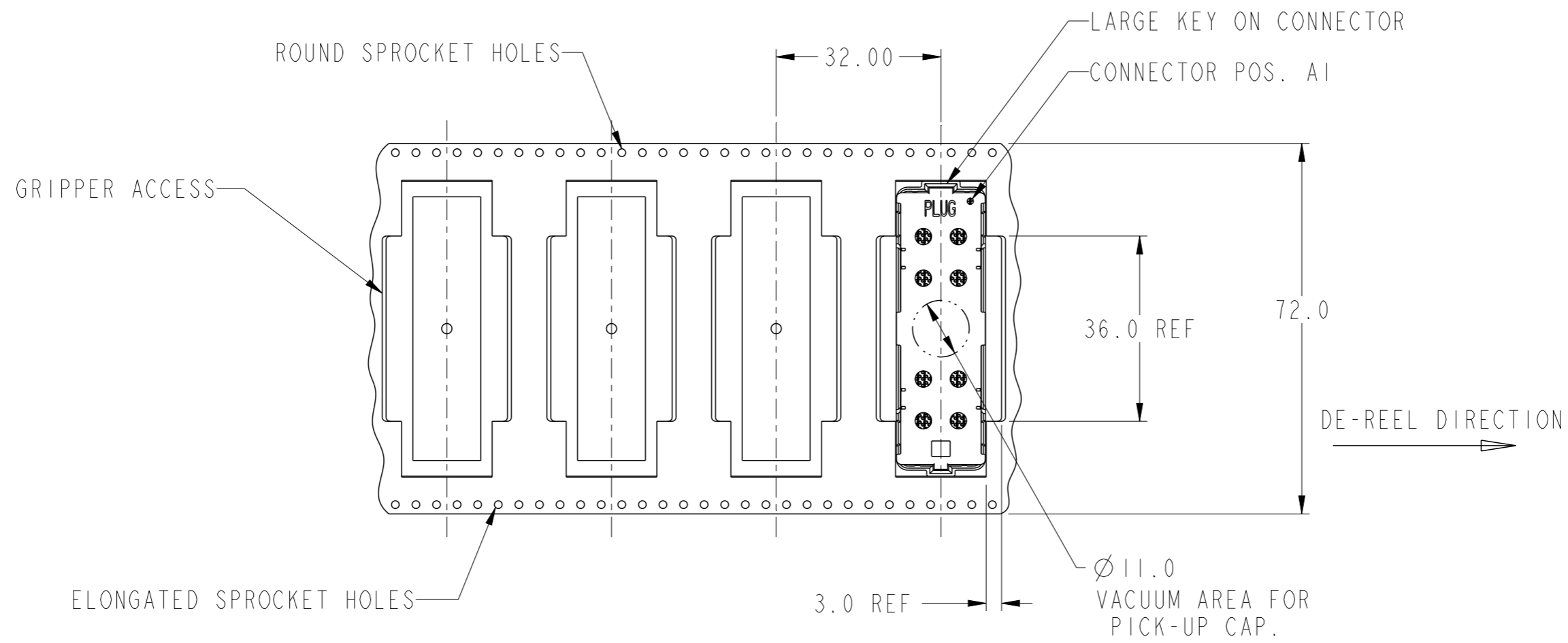
BOARD PATTERN

MATED HEIGHT TABLE		
DIM. "A"	RECPT. ASSY. P/N	-2XX PLATING
10.0	74221	SEE NOTE 4
12.0	74388	SEE NOTE 5
14.0	74390	SEE NOTE 5



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spec ref	-	dr	w cadmin	1999/08/19	projection	mm	size	A3	scale	10:1	
tolerance std	ASME Y14.5	eng	Dave Horchler	2012/11/21			ecn no	ELX-V-13515-1			
		chr	-				rel level	Released			
surface	✓	appr	R Marshall	2012/11/27	product family	MEG-ARRAY		dwg no	84520	rev	H
ASME Y14.5	angular	0°	±2°	www.fci.com	cat. no.	Product - Customer Drw		sheet 2 of 5			



TAPE & REEL PACKAGING
PER EIA 481-3



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spec ref	-	dr	w cadmin	1999/08/19	projection	mm	size	A3	scale	2:1
tolerance std	ASME Y14.5	eng	Dave Horchler	2012/11/21			ecn no		ELX-V-13515-1	
		chr	-				rel level		Released	
surface	✓	appr	R Marshall	2012/11/27	product family	MEG-ARRAY		rev		H
				title 6.0mm PLUG ASSEMBLY 10 X 40 = 400 POSITIONS		dwg no		sheet 3 of 5		
ASME Y14.5	angular	0°	±2°	www.fci.com	cat. no.	Product - Customer Drw		sheet 3 of 5		

PRODUCT NUMBER

SEE TABLE

NOTES:

1. MATERIAL:
HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING:
CONTACT: SEE TABLE ON SHEET 4
SOLDER BALL: SEE TABLE ON SHEET 4
EUTECTIC SnPb OR LEAD FREE
95.5Sn/4Ag/0.5Cu

2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.

3. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE & SOLDER PASTE.

4. PLATING FOR INDICATED -2XX SERIES PRODUCT NUMBERS MEET THE REQUIREMENTS OF GR-1217-CORE, CENTRAL OFFICE ENVIRONMENT, (25 YEAR LIFE EXPECTANCY).

5. PLATING FOR INDICATED -2XX SERIES PART NOS. IS Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEETS REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.

6. KNIT LINE: SLIGHT VISIBLE MARKS (USUALLY A LINE) INDICATING THE DIRECTION AND MEETING POINT OF PLASTIC RESIN FLOW FRONTS TRAVELING AROUND ANY OBSTRUCTIONS TO THE RESIN FLOW VIA THE REQUIRED MOLD TOOLING.

7. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033. LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION.

8. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVE AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004. PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION.

9. 84520-302, -302LF, -402, -402LF, -502 AND -502LF ARE OBSOLETE.

11. A SYMBOL WILL BE NEXT TO ANY DIMENSION, NEW VIEW, OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION.



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spec ref	-	dr	wcadmin	1999/08/19	projection	mm	size	A3	scale	2:1
tolerance std	ASME Y14.5	eng	Dave Horchler	2012/11/21		← →	ecn no		ELX-V-13515-1	
	TOLERANCES UNLESS OTHERWISE SPECIFIED	chr	-	-			product family	MEG-ARRAY	rel level	
surface	✓	appr	R Marshall	2012/11/27	6.0mm PLUG ASSEMBLY		dwg no	54520		rev
	linear				10 X 40 = 400 POSITIONS				H	
	angular				www.fci.com		cat. no.		Product - Customer Drw	
									sheet 5 of 5	